AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 8. (Cancelled)

9. (Currently Amended) A semiconductor device mounting structure including a semiconductor device having an electrode and a substrate having a wiring terminal that is conductively connected to the electrode, wherein

a first electrode pad is mounted to the semiconductor device and covered by the electrode;

a second electrode pad is mounted to the semiconductor device and covered by the electrode;

a width of the wiring terminal is smaller than a width of the electrode;

a recessed portion is formed in a center portion of the electrode ~~before the electrode and the wiring terminal are conductively connected~~, the recessed portion is constituted by a dimension corresponding to the width of the wiring terminal, the recessed portion is opposite to an interval between the first electrode pad and the second electrode pad; and

~~one of the electrode and~~ the wiring terminal is embedded in a surface of the ~~other of the~~ electrode ~~and the wiring terminal~~.

10. – 23. (Cancelled)

24. (Currently Amended) An electro-optical device comprising:

an electro-optical panel retaining an electro-optical substance;

a wiring substrate including a wiring terminal conductively connected to the electro-optical panel; and

a semiconductor device including an electrode conductively connected to the wiring terminal;

wherein:

a first electrode pad is mounted to the semiconductor device and covered by the electrode;

a second electrode pad is mounted to the semiconductor device and covered by the electrode;

a width of the wiring terminal is smaller than a width of the electrode;

a recessed portion is formed in the center portion of the electrode ~~before the electrode and the wiring terminal are conductively connected~~, the recessed portion is constituted by a dimension corresponding to the width of the wiring terminal, the recessed portion is opposite to an interval between the first electrode pad and the second electrode pad; and

the wiring terminal is embedded in a surface of the electrode.